

RS1001FL~RS1008FL

SMALL SURFACE MOUNT FAST DIODES

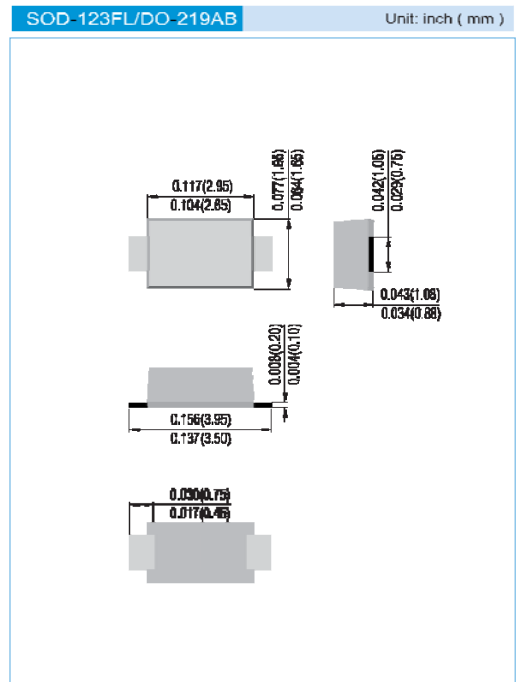
VOLTAGE 100 to 800 Volts **CURRENT** 1.0 Amperes

FEATURES

- For surface mounted applications
- Low profile package
- Ideal for automated placement
- Glass Passivated Chip Junction
- High temperature soldering : 260°C / 10 seconds at terminals
- Pb free product : 99% Sn above can meet RoHS environment substance directive request

MECHANICAL DATA

- Case: JEDEC DO-219AB, Molded plastic over passivated junction
- Terminals: Solderable per MIL-STD-750, Method 2026
- Standard Packaging : 8mm tape (EIA-481)
- Approx. Weight: 0.0168 gram



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%

Rating	Test condition	Symbol	RS1001FL	RS1002FL	RS1004FL	RS1006FL	RS1008FL	Units
Maximum repetitive peak reverse voltage		V_{RRM}	100	200	400	600	800	V
Maximum RMS voltage		V_{RMS}	70	140	280	420	560	V
Maximum DC blocking voltage		V_{DC}	100	200	400	600	800	V
Maximum average forward rectified current	$T_D=65^\circ\text{C}$ $T_A=45^\circ\text{C}$	$I_{F(AV)}$	1.4 0.5					A
Maximum instantaneous forward voltage	0.7A	V_F	1.15					V
Maximum DC reverse current at rated DC blocking voltage	$T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	I_R	10 50					μA
Thermal resistance junction to ambient air		$R_{\theta JA}$	180					K/W
Operating junction and storage temperature range		T_J, T_{STG}	-50 TO + 150					$^\circ\text{C}$
Reverse recovery time	$I_F=0.5\text{A}$ $I_R=1\text{A}$ $t_{rr}=0.25\text{A}$	t_r	150		250		500	nS
Typical capacitance	4V,1MHz	C_J	9					pF

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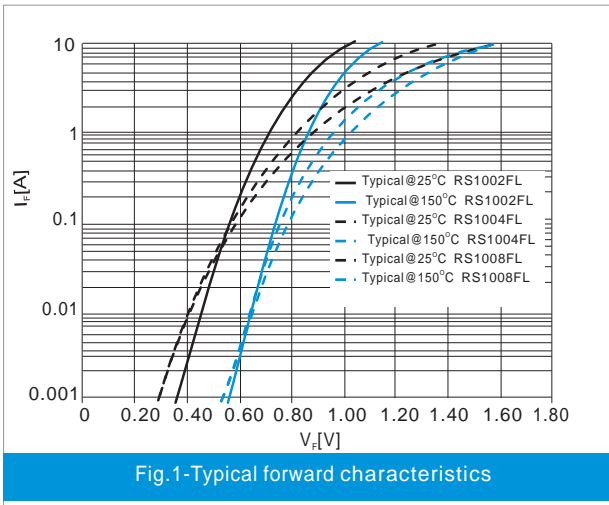


Fig.1-Typical forward characteristics

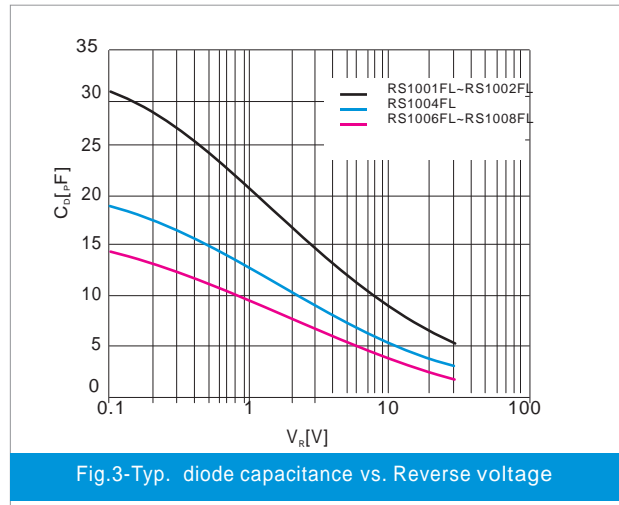


Fig.3-Typ. diode capacitance vs. Reverse voltage

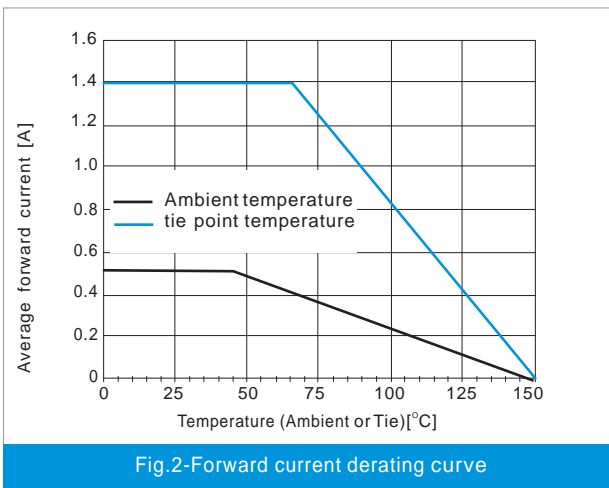


Fig.2-Forward current derating curve